

Title (en)

SEMICONDUCTOR COMPONENT WITH A CHIP CARRIER WITH OPENINGS FOR CONTACTING

Title (de)

HALBLEITERBAUELEMENT MIT EINEM CHIPTRÄGER MIT ÖFFNUNGEN ZUR KONTAKTIERUNG DURCH EINE METALLFOLIE

Title (fr)

COMPOSANT A SEMICONDUCTEUR COMPORTANT UN PORTE-PUCE AVEC DES OUVERTURES POUR LA METALLISATION

Publication

EP 1155449 A1 20011121 (DE)

Application

EP 00912347 A 20000203

Priority

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Abstract (en)

[origin: DE19905055A1] Disclosed is a semiconductor component comprising at least one semiconductor chip (2), a chip carrier (1) for mounting the semiconductor chip (2) onto a first surface (8) of the chip carrier (2) and contact points (6) which are electrically connected to the semiconductor chip (2) and which are provided with a conductive connection via openings (20) of the chip carrier (1) to solder terminals (5) in the area of a second surface (9) of the chip carrier (1). The solder terminals (5) are formed from a metal film (7) which lines the openings (20), extends from the first surface (8) through the openings (20) to the second surface (9) and can be directly contacted. The semiconductor component also comprises an opening (10) in the chip carrier below the semiconductor chip (2). A metal film (11) which lines said opening (10) is situated between the chip carrier (1) and the semiconductor chip (2) so as to form a solder terminal.

IPC 1-7

H01L 23/498; **H01L 23/13**

IPC 8 full level

H01L 23/31 (2006.01); **H01L 23/498** (2006.01); **H05K 3/34** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP US)

H01L 23/3121 (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 23/49816** (2013.01 - EP US); **H01L 23/49827** (2013.01 - EP US); **H05K 3/3436** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/16225** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/32257** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2224/73204** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/85385** (2013.01 - EP US); **H01L 2224/854** (2013.01 - EP US); **H01L 2224/92** (2013.01 - EP US); **H01L 2224/92247** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/15313** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US); **H05K 3/4084** (2013.01 - EP US); **H05K 2201/0394** (2013.01 - EP US); **Y02P 70/50** (2015.11 - EP US)

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